

Pb Free Plating Product

DB101 thru DB107



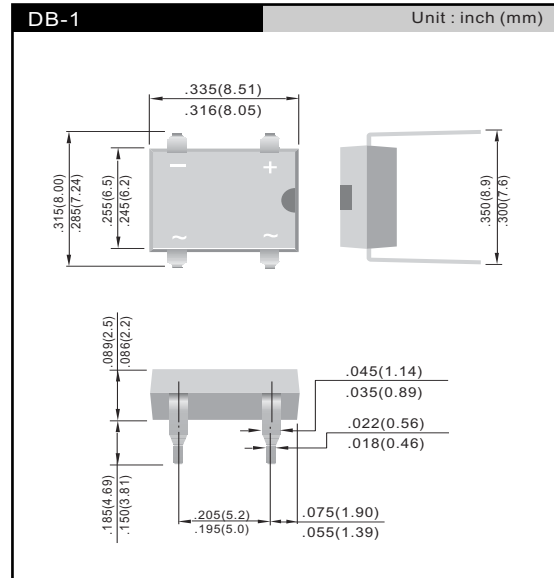
1.0 AMP.DIP GLASS PASSIVATED BRIDGE RECTIFIERS

Features

- Glass passivated chip junction
- Low forward voltage drop
- High surge overload rating of 50 A peak
- Ideal for printed circuit board

Mechanical Data

- Case: Molded plastic, DB
- Epoxy: UL 94V-0 rate flame retardant
- Terminals: Leads solderable per MIL-STD-202, method 208 guaranteed
- Mounting position: Any



Absolute Maximum Ratings and Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Symbols	DB101	DB102	DB103	DB104	DB105	DB106	DB107	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at $T_A = 40^\circ\text{C}$	$I_{(AV)}$	1							A
Peak Forward Surge Current 8.3 ms Single Half-sine-wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	50							A
Maximum Forward Voltage at 1 A	V_F	1.1							V
Maximum Reverse Current at Rated DC Blocking Voltage	I_R	at $T_A = 25^\circ\text{C}$							μA
		at $T_A = 125^\circ\text{C}$							
Typical Junction Capacitance ¹⁾	C_J	25							pF
Typical Thermal Resistance ²⁾	$R_{\theta JA}$	40							$^\circ\text{C/W}$
Typical Thermal Resistance ²⁾	$R_{\theta JL}$	15							$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_S	-55 to +150							$^\circ\text{C}$

¹⁾ Measured at 1 MHz and applied reverse voltage of 4 V

²⁾ Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B with 0.5 X 0.5" (13 X 13 mm) copper pads.

